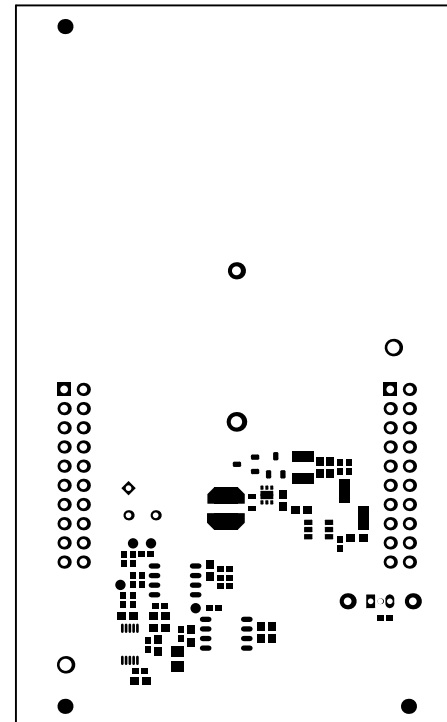
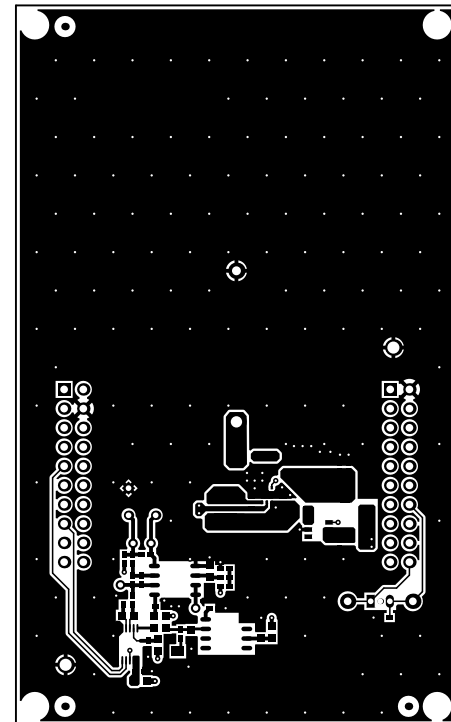


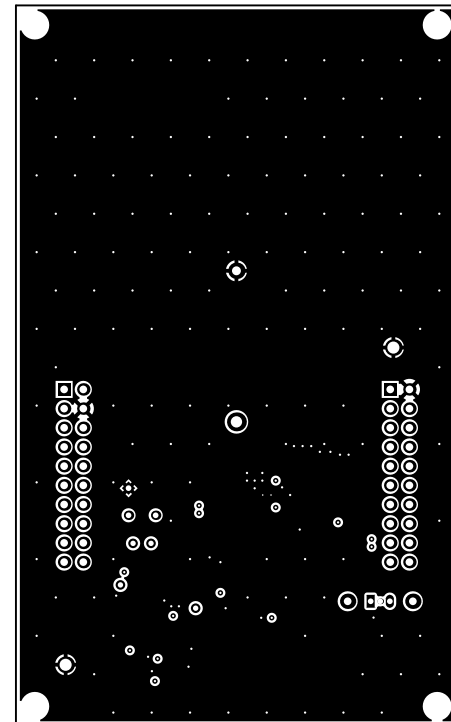
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01469		
PLOT NAME = Top Overlay	GENERATED : 8/11/2017 7:40:24 PM	TEXAS INSTRUMENTS	



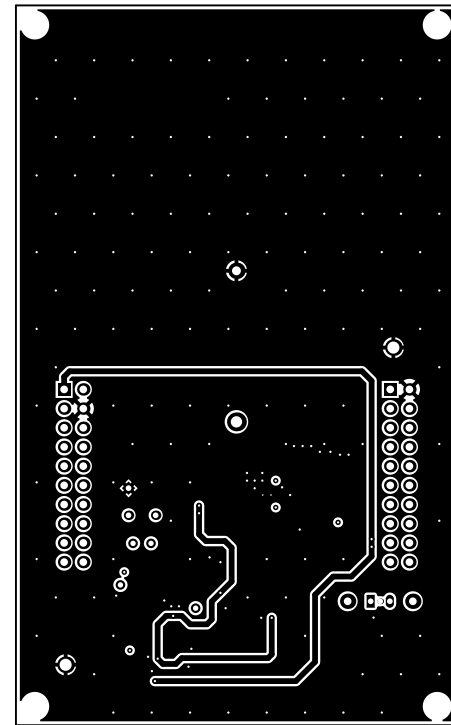
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01469		
PLOT NAME = Top Solder Mask	GENERATED : 8/11/2017 7:40:25 PM	TEXAS INSTRUMENTS	



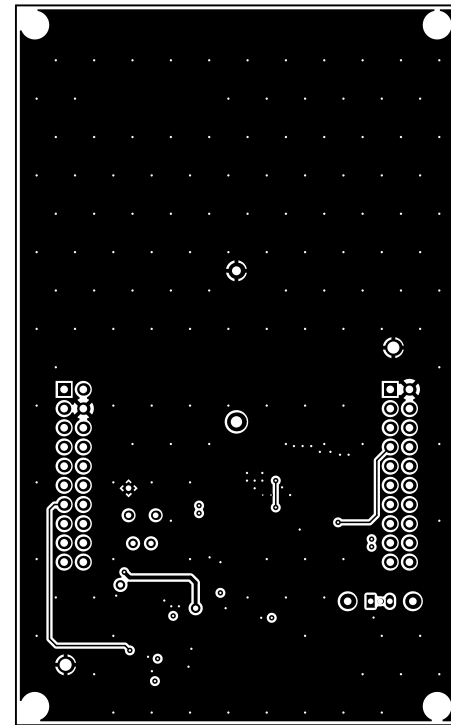
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: TIDA-01469		
PLOT NAME = Top Layer	GENERATED : 8/11/2017 7:40:27 PM	TEXAS INSTRUMENTS	



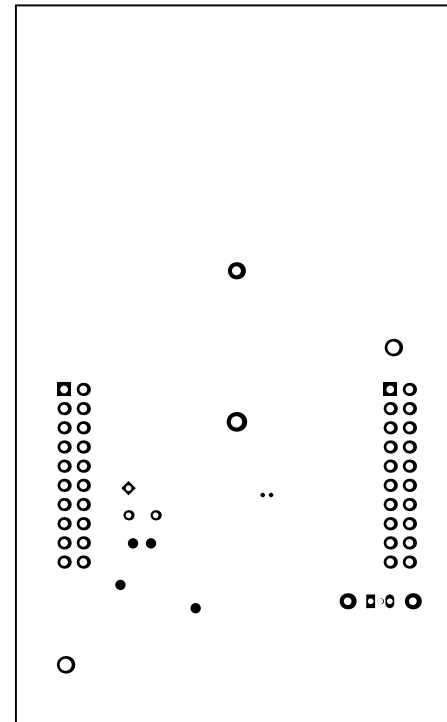
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - GND	TID #: TIDA-01469		
PLOT NAME = Signal Layer 1	GENERATED : 8/11/2017 7:40:28 PM	TEXAS INSTRUMENTS	



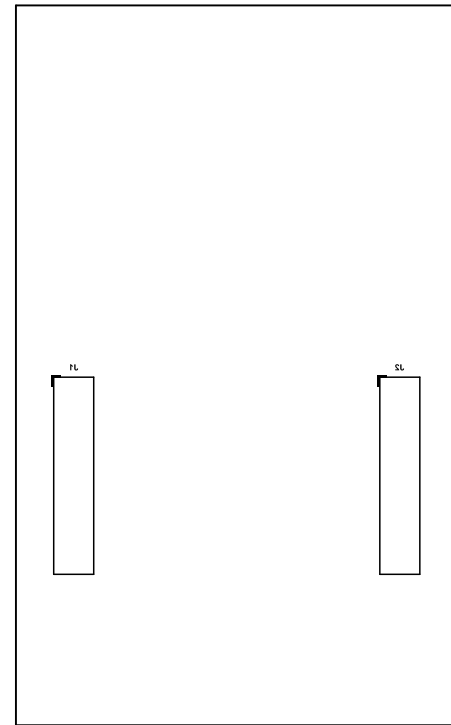
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - PWR	TID #: TIDA-01469		
PLOT NAME = Signal Layer 2	GENERATED : 8/11/2017 7:40:30 PM	TEXAS INSTRUMENTS	



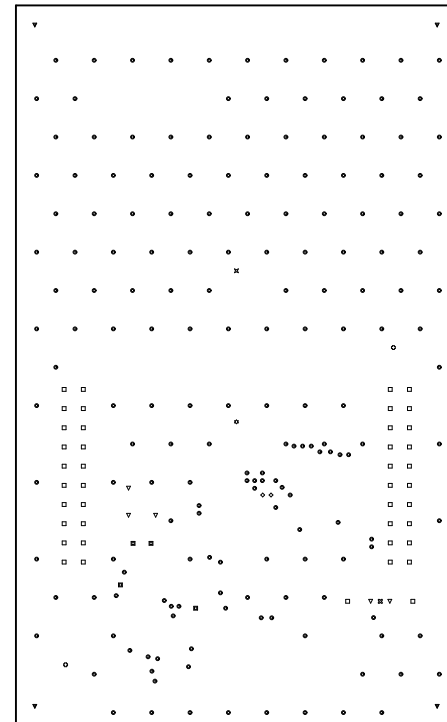
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer	TID #: TIDA-01469		
PLOT NAME = Bottom Layer	GENERATED : 8/11/2017 7:40:31 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01469		
PLOT NAME = Bottom Solder Mask	GENERATED : 8/11/2017 7:40:33 PM	TEXAS INSTRUMENTS	

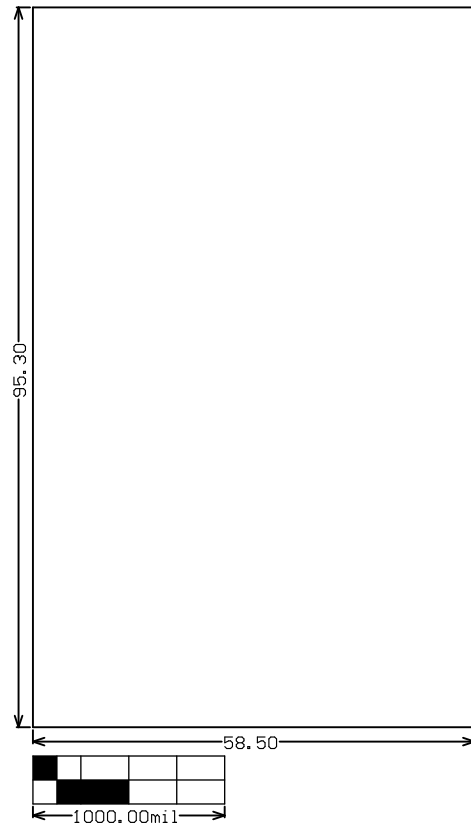


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01469		
PLOT NAME = Bottom Overlay	GENERATED : 8/11/2017 7:40:34 PM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type
⊗	1	29.53mil (0.750mm)	NPTH	Round
⊗	1	46.50mil (1.181mm)	PTH	Round
☆	1	59.06mil (1.500mm)	PTH	Round
◇	2	7.87mil (0.200mm)	PTH	Round
⊕	2	63.00mil (1.600mm)	PTH	Round
⊞	4	28.00mil (0.711mm)	PTH	Round
▽	4	125.98mil (3.200mm)	NPTH	Round
▽	5	29.53mil (0.750mm)	PTH	Round
□	42	40.00mil (1.016mm)	PTH	Round
⊙	178	12.00mil (0.305mm)	PTH	Round
	240 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01469		
PLOT NAME = Drill Drawing	GENERATED : 8/11/2017	7:40:36 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01469	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01469		
PLOT NAME = Board Dimensions	GENERATED : 8/11/2017 7:40:38 PM	TEXAS INSTRUMENTS	

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